PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4491957

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
RISA YAMAKOSHI	06/26/2017
MASATO TERASAKI	06/26/2017
TAKASHI OZAKI	06/26/2017
NAONORI AKAE	06/26/2017
HIDEKI HORITA	06/26/2017

RECEIVING PARTY DATA

Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	15-12, NISHI-SHIMBASHI 2-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8039

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15642791

CORRESPONDENCE DATA

Fax Number: (215)568-6499

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ATTORNEY DOCKET NUMBER:	HITACHI13-0001050US01
NAME OF SUBMITTER:	DANIEL N. CALDER
SIGNATURE:	/Daniel N. Calder/
DATE SIGNED:	07/06/2017

Total Attachments: 7
source=HITACHI13_0001050US01_AssignmentDeclaration_EFS#page1.tif
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Atty. Docket No. HITACHI13-0001050US01

ASSIGNMENT AND DECLARATION

With respect to the invention titled

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, SUBSTRATE PROCESSING APPARATUS, AND RECORDING MEDIUM

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No.__________, filed on __________,

I (the undersigned) hereby state the following.

DECLARATION

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee	**HITACHI KOKUSAI ELECTRIC INC.**
Assignee State or Country of Incorporation	**Japan**
Assignee Address	**15-12, Nishi-shimbashi 2-chome, Minato-ku** **Tokyo 1058039, Japan**

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

SIGNATURE SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name **YAMAKOSHI, Risa**

Inventor's Signature Yamakoshi Risa

Date June 26, 2017

Signed at **Toyama-shi, Japan**
(City and Country)

STATEMENT OF WITNESS (optional):

I, ____________________
Name of Witness

was personally present and did see **YAMAKOSHI, Risa**
inventor identified above

execute this Assignment on ____________ and such Assignor is personally known
date

to me to be the person described herein.

Witness Signature ____________________

An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use a separate form for each inventor; or check the box below and complete the attached page(s) to list additional inventors.

■ Additional inventors are being named on the 4 supplemental sheet(s) attached hereto.

SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name **TERASAKI, Masato**

Inventor's Signature Terasaki, Masato

Date June 26, 2017

Signed at **Toyama-shi, Japan**
(City and Country)

STATEMENT OF WITNESS (optional):

I, ____________________
Name of Witness

was personally present and did see **TERASAKI, Masato**
inventor identified above

execute this Assignment on __________ and such Assignor is personally known
date

to me to be the person described herein.

Witness Signature ____________________

SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name **OZAKI, Takashi**

Inventor's Signature Ozaki, Takashi

Date June 26, 2017

Signed at **Toyama-shi, Japan**
(City and Country)

STATEMENT OF WITNESS (optional):

I, ______________________
Name of Witness

was personally present and did see **OZAKI, Takashi**
inventor identified above

execute this Assignment on ____________ and such Assignor is personally known
date

to me to be the person described herein.

Witness Signature ______________________

SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	**AKAE, Naonori**
Inventor's Signature	AKAE, Naonori
Date	June 26, 2017
Signed at	**Toyama-shi, Japan** (City and Country)

STATEMENT OF WITNESS (optional):

I, ______________________
Name of Witness

was personally present and did see **AKAE, Naonori**
inventor identified above

execute this Assignment on ______________ and such Assignor is personally known
date

to me to be the person described herein.

Witness Signature ______________________

SUPPLEMENTAL SHEET FOR DECLARATION AND ASSIGNMENT

Inventor's Name	**HORITA, Hideki**
Inventor's Signature	Horita Hideki
Date	June 26, 2017
Signed at	**Toyama-shi, Japan** (City and Country)

STATEMENT OF WITNESS (optional):

I, ____________________
Name of Witness

was personally present and did see **HORITA, Hideki**
inventor identified above

execute this Assignment on __________ and such Assignor is personally known
date

to me to be the person described herein.

Witness Signature ____________________